

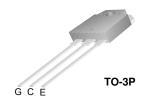
FGA90N30

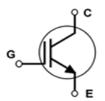
Features

- · High Current Capability
- Low saturation voltage: $V_{CE(sat)}$, Typ = 1.1V@ I_C = 20A
- · High Input Impedance

Description

Employing Unified IGBT Technology, FGA90N30 provides low conduction and switching loss. FGA90N30 offers the optimum solution for PDP applications where low condution loss is essential.





Absolute Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Description		FGA90N30	Units
V _{CES}	Collector-Emitter Voltage		300	V
V _{GES}	Gate-Emitter Voltage		± 30	V
I _C	Collector Current	@ T _C = 25°C	90	A
I _{CM}	Pulsed Collector Current (Note 1)	@ T _C = 25°C	220	Α
P_{D}	Maximum Power Dissipation	@ T _C = 25°C	219	W
	Maximum Power Dissipation	@ T _C = 100°C	87	W
T _J	Operating Junction Temperature		-55 to +150	°C
T _{stg}	Storage Temperature Range		-55 to +150	°C
TL	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C

Notes

(1) Repetitive test , pulse width = 100usec , Duty = 0.2

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction-to-Case for IGBT		0.57	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	-	40	°C/W

^{*} Ic_pulse limited by max Tj

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FGA90N30	FGA90N30	TO-3P			30

Electrical Characteristics of the IGBT $T_C = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Charac	eteristics					
BV _{CES}	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250\mu A$	300			V
ΔB _{VCES} / ΔΤ _J	Temperature Coefficient of Breakdown Voltage	V _{GE} = 0V, I _C = 250μA		0.6		V/°C
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$			100	μА
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$			± 250	nA
On Charac	teristics					
V _{GE(th)}	G-E Threshold Voltage	I _C = 250uA, V _{CE} = V _{GE}	2.5	4.0	5.0	V
		I _C = 20A, V _{GE} = 15V		1.1	1.4	V
V	Callactor to Emitter	I _C = 90A, V _{GE} = 15V		1.9		V
V _{CE(sat)}	Collector to Emitter Saturation Voltage	I _C = 90A, V _{GE} = 15V, T _C = 125°C		2.0		V
Dynamic C	Characteristics	,			II.	I.
C _{ies}	Input Capacitance			1700	-	pF
C _{oes}	Output Capacitance	$V_{CE} = 30V, V_{GE} = 0V,$		290	-	pF
C _{res}	Reverse Transfer Capacitance	f = 1MHz		80	-	pF
Switching	Characteristics			ı	I	
t _{d(on)}	Turn-On Delay Time			30		ns
t _r	Rise Time			200		ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 200V, I_C = 20A,$		110		ns
t _f	Fall Time	$R_G = 10\Omega$, $V_{GE} = 15V$, Resistive Load, $T_C = 25^{\circ}C$		140	300	ns
E _{on}	Turn-On Switching Loss	- Nesiotive Load, 16 25 6		0.15		mJ
E _{off}	Turn-Off Switching Loss	_		0.45		mJ
E _{ts}	Total Switching Loss			0.6		mJ
t _{d(on)}	Turn-On Delay Time			30		ns
t _r	Rise Time			210		ns
$t_{d(off)}$	Turn-Off Delay Time	V_{CC} =200V, I_{C} = 20A,		110		ns
t _f	Fall Time	$R_G = 10\Omega$, $V_{GE} = 15V$, Resistive Load, $T_C = 125$ °C		200		ns
E _{on}	Turn-On Switching Loss			0.16		mJ
E _{off}	Turn-Off Switching Loss			0.72		mJ
E _{ts}	Total Switching Loss			0.88		mJ
Qg	Total Gate Charge	V _{CE} = 200V, I _C = 20A,		87	130	nC
Q _{ge}	Gate-Emitter Charge	V _{GE} = 15V		12	18	nC

Typical Performance Characteristics

Figure 1. Typical Output Characteristics

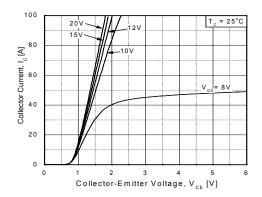


Figure 2. Typical Output Characteristics

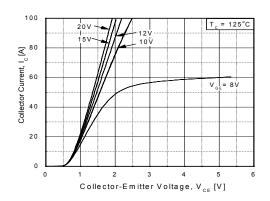


Figure3. Typical Saturation Voltage Characteristics

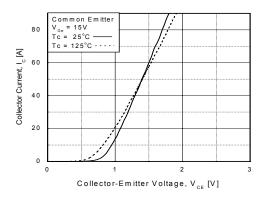


Figure 4. Transfer characteristics

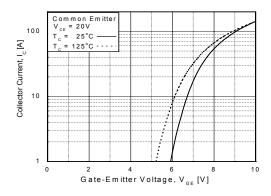


Figure 5. Saturation Voltage vs. Case
Temperature at Variant Current Level

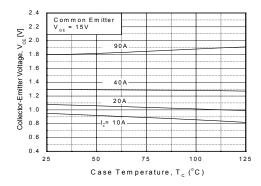
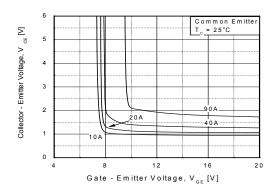


Figure 6. Saturation Voltage vs. V_{GE}



Typical Performance Characteristics (Continued)

Figure 7. Saturation Voltage vs. V_{GE}

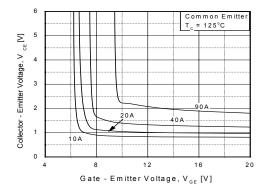


Figure 8. Capacitance Charaacteristics

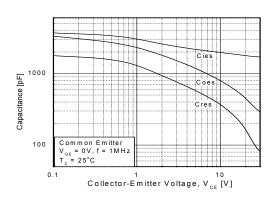


Figure 9. Gate Charge Characteristics

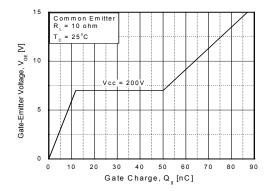


Figure 10. SOA Characteristics

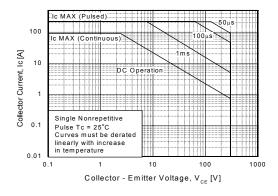


Figure 11. Turn-On Characteristics vs. Gate Resistance

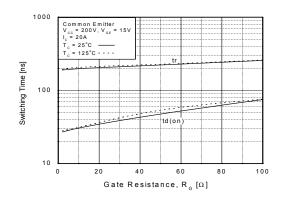
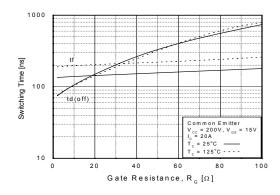


Figure 12. Turn-Off Characteristics vs. Gate Resistance



Typical Performance Characteristics (Continued)

Figure 13. Turn-On Characteristics vs. Collector Current

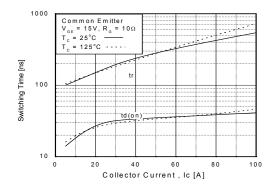


Figure 14.Turn-Off Characteristics vs. Collector Current

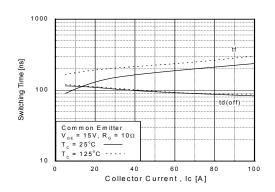


Figure 15. Switching Loss vs. Gate Resistance

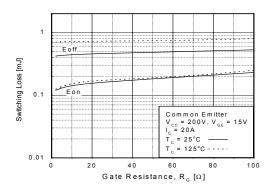


Figure 16.Switching Loss vs. Collector Current

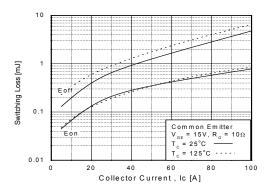
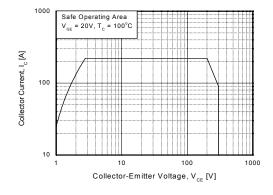
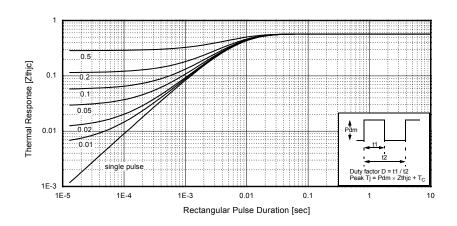


Figure 17. Turn-Off SOA Figure



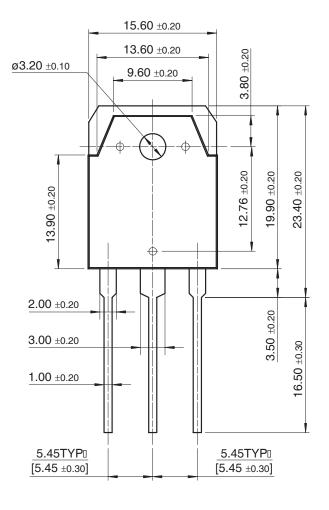
Typical Performance Characteristics (Continued)

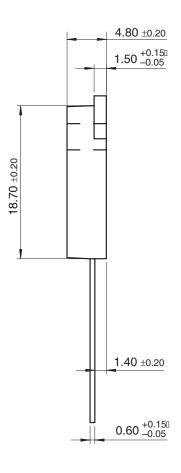
Figure 18. Transient Thermal Impedance of IGBT



Mechanical Dimensions

TO-3P





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FGA90N30

300V PDP IGBT

Contents

- General description
- Features
- Product status/pricing/packaging
- Order Samples

General description

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back to top

Features

- High Current Capability
- Low saturation voltage: V_{CE(sat)}, Typ = 1.1V@ I_C = 20A
- High Input Impedance

back to top

Product status/pricing/packaging

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back to top

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